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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Chuen Rong Leu et al.  
Assignee: Bridge Semiconductor Corporation  
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP  
ASSEMBLY WITH AN EMBEDDED METAL PILLAR  
Serial No.: 10/719,823 Filed: November 21, 2003  
Examiner: Unknown Group Art Unit: 2812  
Atty. Docket No.: BDG024-1

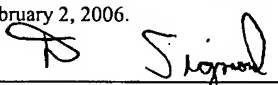
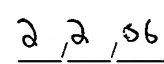
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COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313

**TRANSMITTAL OF FORMAL DRAWINGS**

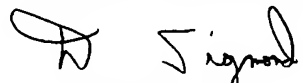
In response to the Notice of Non-Compliant Amendment dated January 30, 2006, formal drawings (36 sheets) are attached with "Replacement Sheet" labeled in the top margin.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 2, 2006.

   
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Attorney for Applicant

2/2/06  
\_\_\_\_\_  
Date of Signature

Respectfully submitted,



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